MYCRONIC

MYPro series A41DX/SX™
pick-and-place

Specifications
November 2025

Specifications MYPro series **A41DX/SX™**

PLACEMENT SPEED AND ACCURACY

	A41DX	A41SX
Rated speed [1]	49,000CPH	24,000CPH
IPC 9850 chip net throughput [2, 3]	31,000CPH	15,000CPH
IPC 9850 chip throughput [3]	35,000CPH	17,000CPH
IPC 9850 chip repeatability 3σ (X, Y, Theta) [6]	30µm, 1.8° [5] 45µm, 1.8°	30µm, 1.8° [5] 45µm, 1.8°
IPC 9850 QFP repeatability 3σ (X, Y, Theta) [4]	21µm, 0.054° [9] 30µm, 0.12° [6, 8] 45µm, 0.21° [8]	21µm, 0.054° [7] 30µm, 0.12° [5, 6] 45µm, 0.21° [6]

The above specification achieved with a machine configuration including high precision mounthead (Midas), high speed mounthead (MX7), line scan vision system (LVS), inline conveyor T1000 and 15mm component maximum height. The IPC 9850 net throughput and accuracy numbers are obtained simultaneously, with the same machine settings. The rated speed value is obtained under conditions optimized for speed.

(1) Depending on component and application
(2) According to IPC 9850. Net throughput = (no of parts x 3,600)/(board build time + board transfer time)
(3) According to IPC 9850 0402C verification panel
(4) According to IPC 9850 QFP64/QFP100 verification panel
(5) High precision setting, recommended for small chip or fine pitch
(6) High-speed mounthead—MX7
(7) High-precision mounthead—MIDAS

SYSTEM FEATURES

A41DX/SX
On-the-fly mount order optimization
Vision autoteach with snap-to-grid
Automatic illumination settings
Intelligent feeder concept—Agilis
Automatic feeder and component recognition
On-the-fly feeder loading
Dynamic feeder positions
Automatic board stretch compensation
Automatic conveyor width adjustment
Intelligent surface impact control
Tool collision avoidance
Multi-user, multi-tasking system software
Open software interfaces for factory integration
SQL database engine
Hermes

COMPONENT RANGE

HIGH PRECISION MOUNTHEAD—MIDAS

Component specification	Min: 0.3 x 0.15mm (0.012 x 0.006") (03015) Max: 99 x 73 x 15mm (3.89 x 2.87 x 0.86") [1] [3] Max component weight: 140g [2]

(1) With 4K vision. Customized tall component capability 22mm (0.86") available.
(2) Depending on mounthead, mount tool, package, and production altitude.
(3) Components with diagonal larger than 58mm must be presented in the same angle as placed.

HIGH SPEED MOUNTHEAD—MX7

Component specification	Min: 0.4 x 0.2mm (0.016 x 0.008") (01005) Max: 45 x 45 x 15mm (1.77 x 1.77 x 0.59") [1] Max: 150 x 40 x 15mm (5.90 x 1.57 x 0.59") [1]

(1) Components with diagonal larger than 52mm will if needed be rotated over the place area. Maximum component weight: 80g

ELECTRICAL VERIFIER (OPTIONAL)

Component range	Resistor, capacitor, unipolar capacitor, diode (forward voltage, reverse current), Zener diode (reverse voltage), bipolar transistor (current gain), FET/IGBT (gate threshold voltage). Smallest chip size 1.0 x 0.5mm (0.04 x 0.02").

FEEDER CAPACITY

8MM TAPE	T1000
A41DX/SX	176

BOARD HANDLING

	T1000
Maximum board size	1,000 x 609mm (39 x 24")
Minimum board size [1]	120 x 50mm (4.7 x 2")
Maximum board train length	472mm (18.5")
Board thickness range [5]	0.8–12.5mm (0.03–0.5")
Board edge clearance top	3.2mm (0.13")
Board edge clearance bottom [2]	3.5mm (0.13")
Top side clearance (max)	15mm (0.59")
Bottom side clearance (max) [3]	32mm (1.25")
Maximum board weight	10kg (22lbs)
Board transfer height	Conforms to SMEMA standard for board transfer height. Height adjustable from 880 to 975mm (34.6 to 38.4").
Operation mode	Inline, manual, inline odd-board, left-to-right/right-to-left.

(1) Board train specification: 100 x 50mm (4.7 x 2") board size, 1.6mm (0.06") minimum thickness. Maximum warpage 1mm (0.04").
(2) Edge clearance 5.5mm (0.22") if component taller than 6mm (0.24"). 14.3mm (0.56") if taller than 19mm (0.75").
(3) Customized tall component capability 22mm (0.86") available.
(4) 15mm (0.59") with support pins.
(5) For tall component capability 22mm. Board thickness 0.8–5.5mm.

VISION CAPABILITY

LINESCAN VISION SYSTEM—4K RESOLUTION

Component type	Field of view	Minimum pitch	Minimum lead width
Leaded components	80mm (3.1")	0.10mm (4mil)	0.05mm (2mil)
Bumped components	80mm (3.1")	0.15mm (6mil)	0.08mm (3mil)

LINESCAN VISION SYSTEM—2K RESOLUTION

Component type	Field of view	Minimum pitch	Minimum lead width
Leaded components	63mm (2.5")	0.20mm (8mil)	0.10mm (4mil)
Bumped components	63mm (2.5")	0.25mm (10mil)	0.13mm (5mil)

SOFTWARE

SOFTWARE MODULES (OPTIONAL)

Shared databases
PCB ID (2D barcode)
Pre-pick inspection
Barcode software
PRM (Proactive Replenishment Monitoring) software
Hermes

OFFLINE SOFTWARE TOOLS (OPTIONAL)

Data preparation—MYCenter
Optimization and scheduling—MYPlan
Inventory management and kitting—MYCenter
Traceability—MYTrace
Performance monitoring—MYCenter Analysis

MISCELLANEOUS

INSTALLATION REQUIREMENTS

Power requirements	Three phase AC 6.6kVA (3x2.2kVA)
Power consumption	1.5kW (average)
Voltages	3x200, 210, 220, 230, 240, 250±10%, Y or Delta
Air supply	No air required
Air temperature	+18 to +35°C (65 to 95°F)
Air humidity	<95% RH non condensing

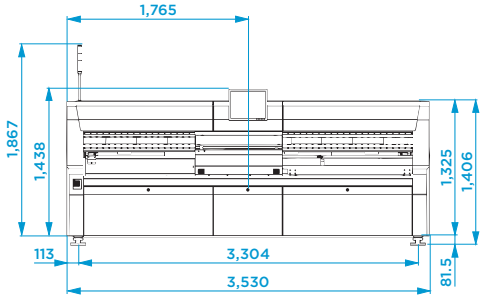
MACHINE WEIGHT (1)

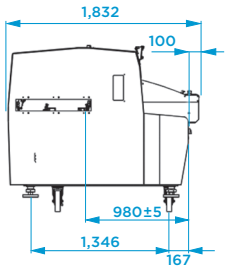
A41DX/SX	2,200kg (4,850lbs)

(1) Total machine weight excluding magazines.

DIMENSIONS [mm]

A41DX/SX





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